



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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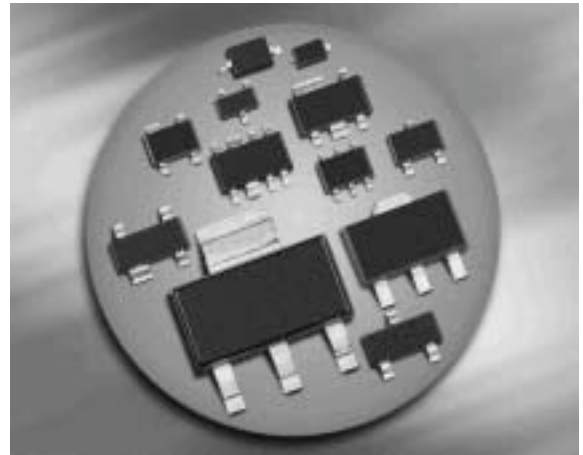
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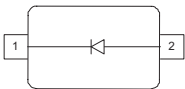


Medium Power AF Schottky Diode

- Forward current: 750 mA
Reverse voltage: 40 V
- For low-loss, fast-recovery, meter protection, bias isolation and clamping applications
- Pb-free (RoHS compliant) package¹⁾
- Qualified according AEC Q101



BAT165



ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Package	Configuration	Marking
BAT165	SOD323	single	C/White

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage ²⁾	V_R	40	V
Forward current ²⁾	I_F	750	mA
Average rectified forward current (50/60Hz, sinus)	I_{FAV}	500	mA
Non-repetitive peak surge forward current ($t \leq 10\text{ms}$)	I_{FSM}	2.5	A
Total power dissipation $T_S \leq 93^\circ\text{C}$	P_{tot}	600	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ³⁾	R_{thJS}	≤ 95	K/W

¹⁾Pb-containing package may be available upon special request

²⁾For $T_A > 25^\circ\text{C}$ the derating of V_R and I_F has to be considered. Please refer to the attached curves.

³⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

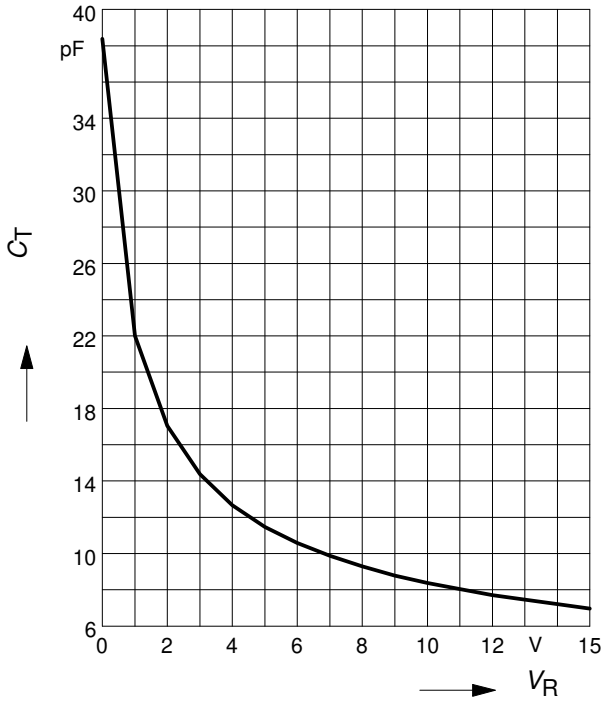
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Reverse current ¹⁾	I_R				μA
$V_R = 30\text{ V}$		-	-	12	
$V_R = 40\text{ V}$		-	-	50	
$V_R = 40\text{ V}, T_A = 65^\circ\text{C}$		-	-	900	
Forward voltage	V_F				V
$I_F = 10\text{ mA}$		0.23	0.315	0.4	
$I_F = 100\text{ mA}$		0.32	0.39	0.47	
$I_F = 250\text{ mA}$		0.35	0.44	0.54	
$I_F = 750\text{ mA}$		0.44	0.58	0.74	
AC Characteristics					
Diode capacitance	C_T	-	8.4	12	pF
$V_R = 10\text{ V}, f = 1\text{ MHz}$					

¹Pulsed test: $t_p = 300\ \mu\text{s}; D = 0.01$

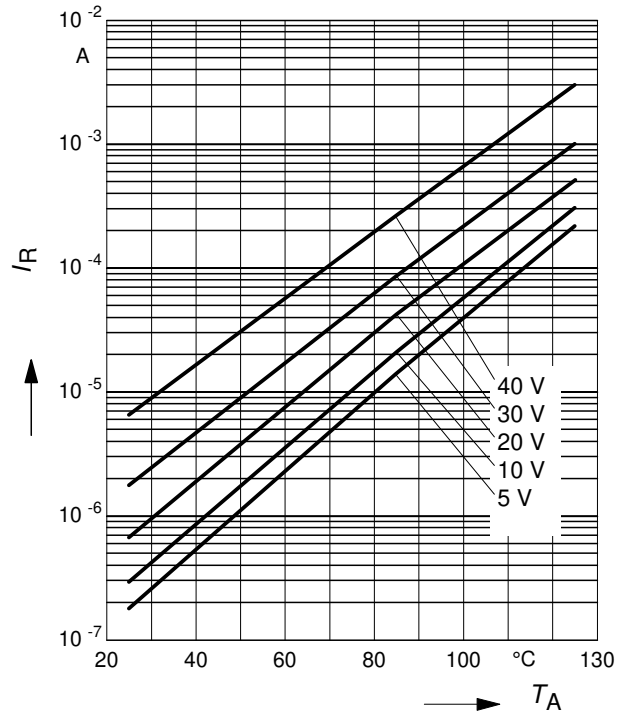
Diode capacitance $C_T = f(V_R)$

$f = 1\text{MHz}$



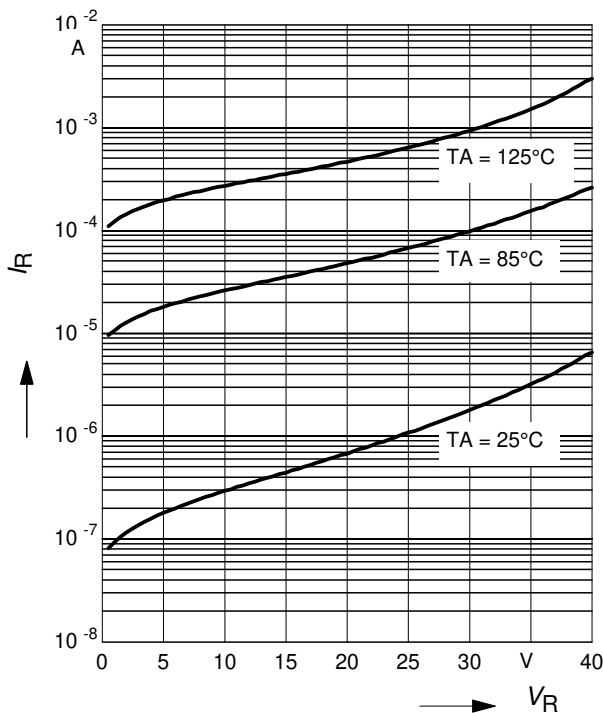
Reverse current $I_R = f(T_A)$

$V_R = \text{Parameter}$



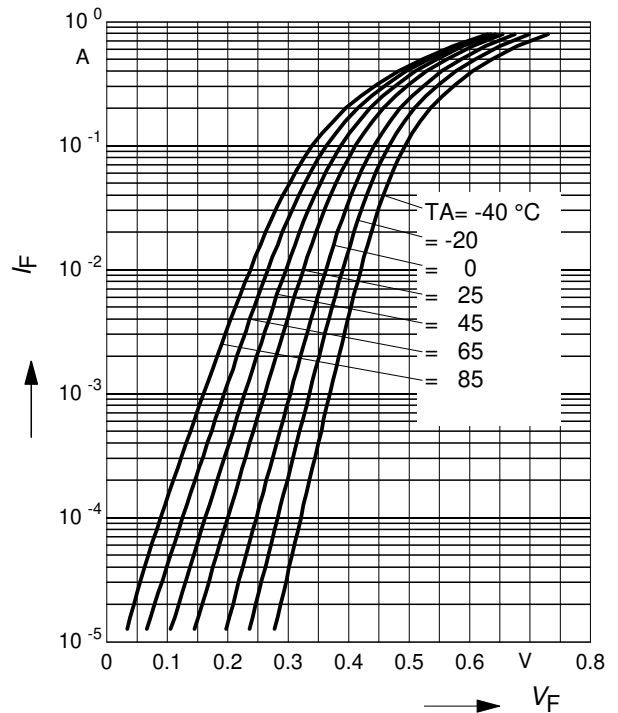
Reverse current $I_R = f(V_R)$

$T_A = \text{Parameter}$



Forward current $I_F = f(V_F)$

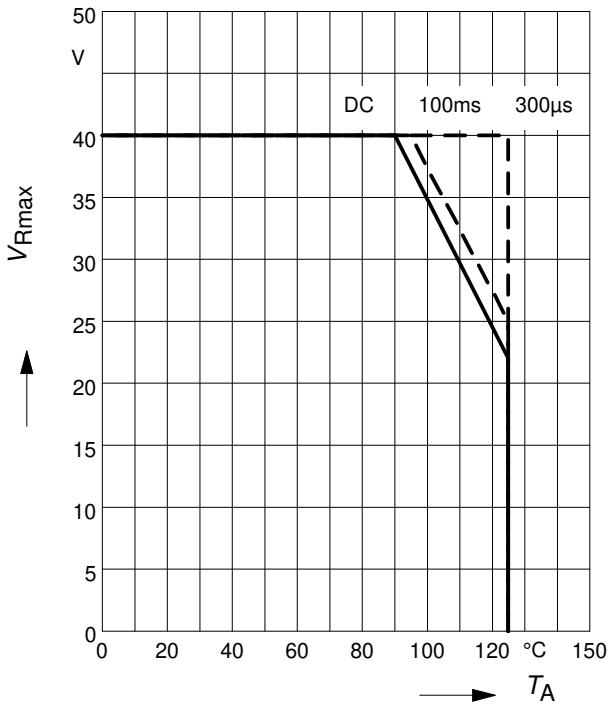
$T_A = \text{Parameter}$



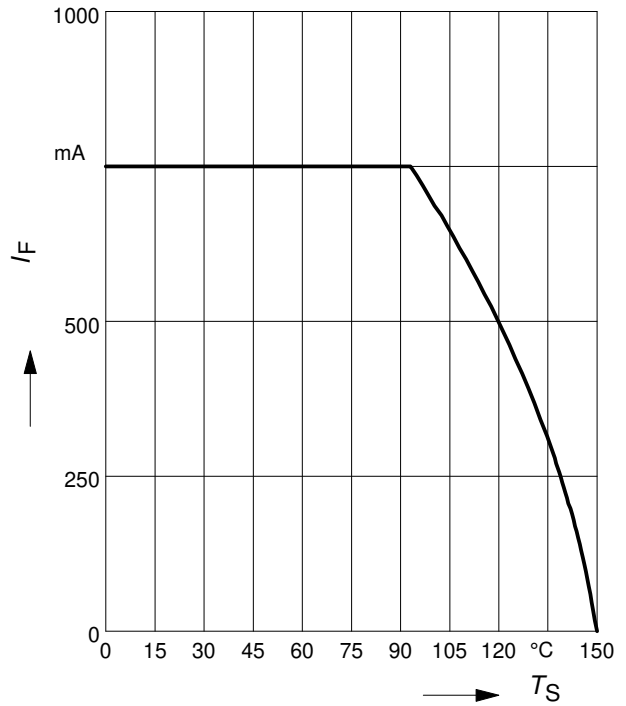
Permissible Reverse voltage $V_R = f(T_A)$

t_p = Parameter, Duty cycle < 0.01

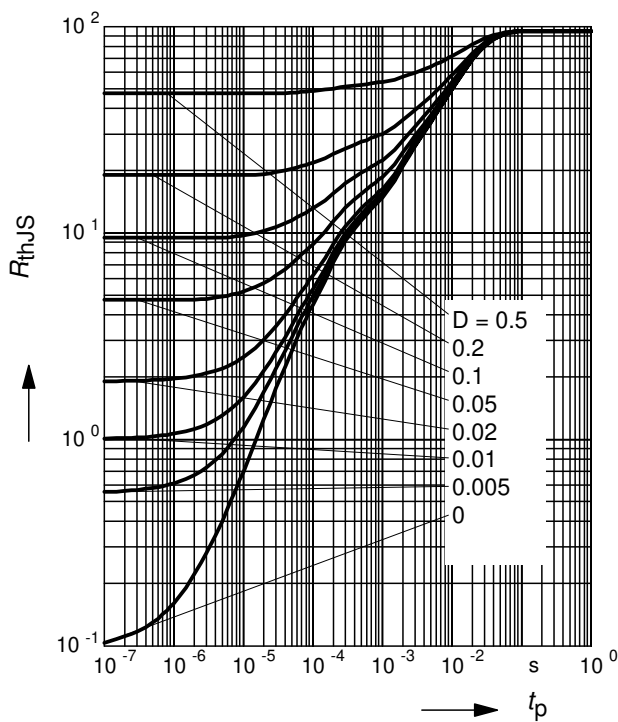
Device mounted on PCB with $R_{th} = 160 \text{ k/W}$



Forward current $I_F = f(T_S)$

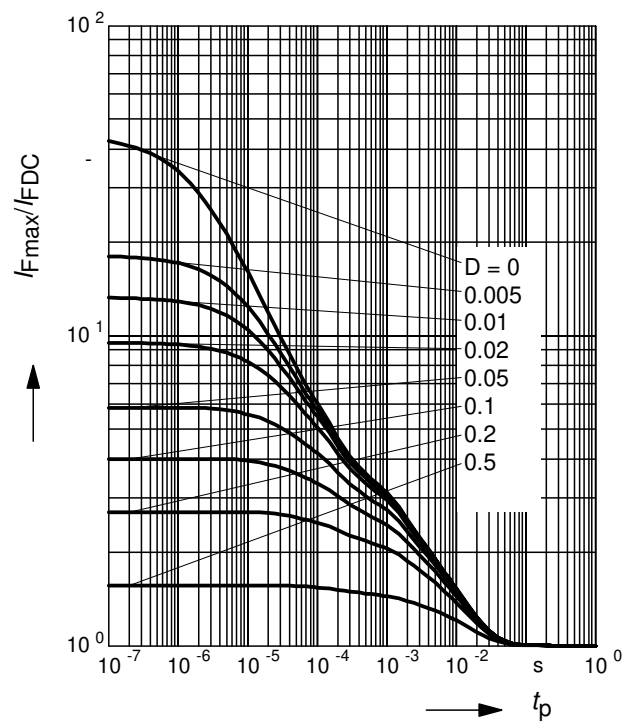


Permissible Puls Load $R_{thJS} = f(t_p)$

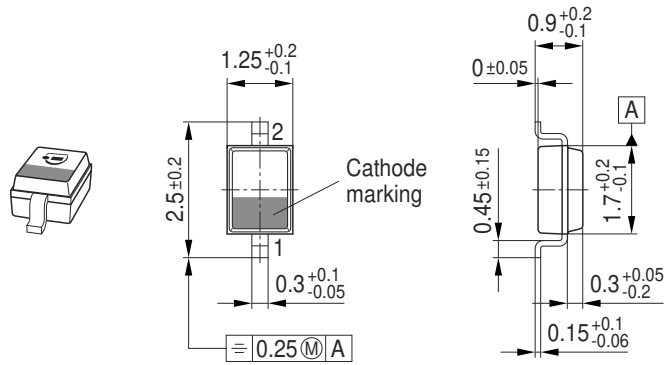


Permissible Pulse Load

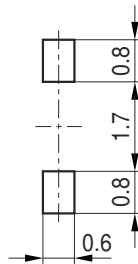
$I_{Fmax} / I_{FDC} = f(t_p)$



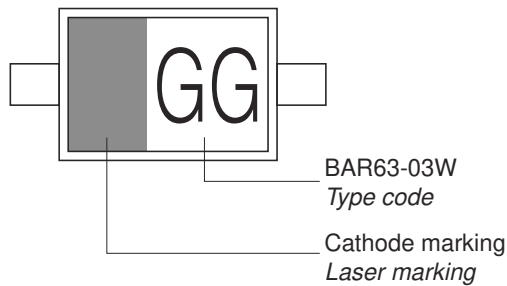
Package Outline



Foot Print

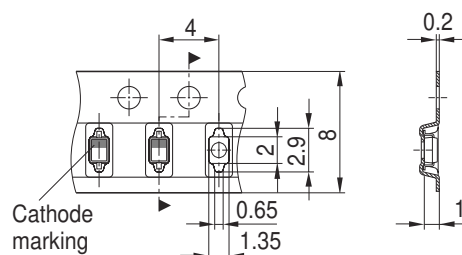


Marking Layout (Example)



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



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